High Density Packaging

ULVAC Solutions

High Density Packaging Technology / Manufacturing Process

Process Flow	● Available Systems
Front end process	
UBM Pad Formation	Etching System • Evaporation System • Sputtering System
Patterning	Etching System
Rewiring	Evaporation System • Sputtering System
Patterning	Etching System
Bump Formation	Evaporation System
Reflow	
PCB Connection	

High Density Packaging

Product for Solutions

Sputtering System for CSP

SRH-820

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- Available for max. 8 inch substrate
  Available for small-size substrate by the change of substrate holders.
- Available for max. 7 processes
  Be able to select max. 7 positions for heating, etching, sputtering treatment chamber.
- Available for high-throughput process
  Be able to treat single substrate at the shortest time - 35 sec.

Dry Etching System for UBM

APIOS NE-7800

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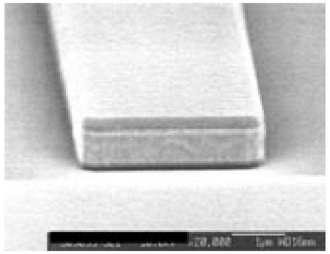

Metal/Au/Metal

- Available for lump etching of UBM (Ti, Cr, Au, Cu, TiW, Ni) High Density Plasma Etching System
- Best modification for sputter-like metal etching and post-treatment (residuals-free)
- Excellent repeatability and stability
- Available for multi-chamber (3 chamber)
- High cost performance